



TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1, 11, 14, 24, 25, 35, 38, 48	V _{CCO}	Power		Output supply pins.
2, 3	Q11, nQ11	Output		Differential output pair. LVPECL interface levels.
4, 5	Q10, nQ10	Output		Differential output pair. LVPECL interface levels.
6, 19, 30, 43	V _{EE}	Power		Negative supply pins.
7, 8	Q9, nQ9	Output		Differential output pair. LVPECL interface levels.
9, 10	Q8, nQ8	Output		Differential output pair. LVPECL interface levels.
12, 13	V _{CC}	Power		Core supply pins.
15, 16	Q7, nQ7	Output		Differential output pair. LVPECL interface levels.
17, 18	Q6, nQ6	Output		Differential output pair. LVPECL interface levels.
20, 21	Q5, nQ5	Output		Differential output pair. LVPECL interface levels..
22, 23	Q4, nQ4	Output		Differential output pair. LVPECL interface levels.
26, 27	Q3, nQ3	Output		Differential output pair. LVPECL interface levels.
28, 29	Q2, nQ2	Output		Differential output pair. LVPECL interface levels.
36	CLK	Input	Pulldown	Non-inverting differential clock input.
37	nCLK	Input	Pullup	Inverting differential clock input.
39, 40	Q15, nQ15	Output		Differential output pair. LVPECL interface levels.
41, 42	Q14, nQ14	Output		Differential output pair. LVPECL interface levels.
44, 45	Q13, nQ13	Output		Differential output pair. LVPECL interface levels.
46, 47	Q12, nQ12	Output		Differential output pair. LVPECL interface levels.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
R _{PULLUP}	Input Pullup Resistor			51		kΩ
R _{PULLDOWN}	Input Pulldown Resistor			51		kΩ

TABLE 3. FUNCTION TABLE

Inputs		Outputs		Input to Output Mode	Polarity
CLK	nCLK	Q0:Q15	nQ0:nQ15		
0	1	LOW	HIGH	Differential to Differential	Non Inverting
1	0	HIGH	LOW	Differential to Differential	Non Inverting
0	Biased; NOTE 1	LOW	HIGH	Single Ended to Differential	Non Inverting
1	Biased; NOTE 1	HIGH	LOW	Single Ended to Differential	Non Inverting
Biased; NOTE 1	0	HIGH	LOW	Single Ended to Differential	Inverting
Biased; NOTE 1	1	LOW	HIGH	Single Ended to Differential	Inverting

NOTE 1: Please refer to the Application Information section, "Wiring the Differential Input to Accept Single Ended Levels".



ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{CC}	4.6V
Inputs, V_I	-0.5V to $V_{CC} + 0.5V$
Outputs, I_O	
Continuous Current	50mA
Surge Current	100mA
Package Thermal Impedance, θ_{JA}	47.9°C/W (0 lfpm)
Storage Temperature, T_{STG}	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 4A. POWER SUPPLY DC CHARACTERISTICS, $V_{CC} = V_{CCO} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{CC}	Input/core Supply Voltage		3.135	3.3	3.465	V
V_{CCO}	Output Supply Voltage		3.135	3.3	3.465	V
I_{EE}	Power Supply Current				140	mA

TABLE 4B. DIFFERENTIAL DC CHARACTERISTICS, $V_{CC} = V_{CCO} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
I_{IH}	Input High Current	CLK $V_{CC} = V_{IN} = 3.465V$			150	μA
		nCLK $V_{CC} = V_{IN} = 3.465V$			5	μA
I_{IL}	Input Low Current	CLK $V_{CC} = 3.465V, V_{IN} = 0V$	-5			μA
		nCLK $V_{CC} = 3.465V, V_{IN} = 0V$	-150			μA
V_{PP}	Peak-to-Peak Input Voltage		0.15		1.3	V
V_{CMR}	Common Mode Input Voltage; NOTE 1, 2		$V_{EE} + 0.5$		$V_{CC} - 0.85$	V

NOTE 1: For single ended applications, the maximum input voltage for CLK, nCLK is $V_{CC} + 0.3V$.

NOTE 2: Common mode voltage is defined as V_{IH} .

TABLE 4C. LVPECL DC CHARACTERISTICS, $V_{CC} = V_{CCO} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OH}	Output High Voltage; NOTE 1		$V_{CCO} - 1.4$		$V_{CCO} - 0.9$	V
V_{OL}	Output Low Voltage; NOTE 1		$V_{CCO} - 2.0$		$V_{CCO} - 1.7$	V
V_{SWING}	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with 50Ω to $V_{CCO} - 2V$.



TABLE 5. AC CHARACTERISTICS, $V_{CC} = V_{CCO} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency				500	MHz
t_{PD}	Propagation Delay; NOTE 1	$f \leq 500MHz$	1		2	ns
$tsk(o)$	Output Skew; NOTE 2, 4				75	ps
$tsk(pp)$	Part-to-Part Skew; NOTE 3, 4			88	250	ps
t_{jit}	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter Section	106.25MHz, Integration Range: 12KHz to 20MHz		0.03		ps
t_R	Output Rise Time	20% to 80% @ 50MHz	300		700	ps
t_F	Output Fall Time	20% to 80% @ 50MHz	300		700	ps
odc	Output Duty Cycle		47	50	53	%

All parameters measured at 250MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.
Measured at the output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages
and with equal load conditions. Using the same type of inputs on each device, the outputs are measured
at the differential cross points.

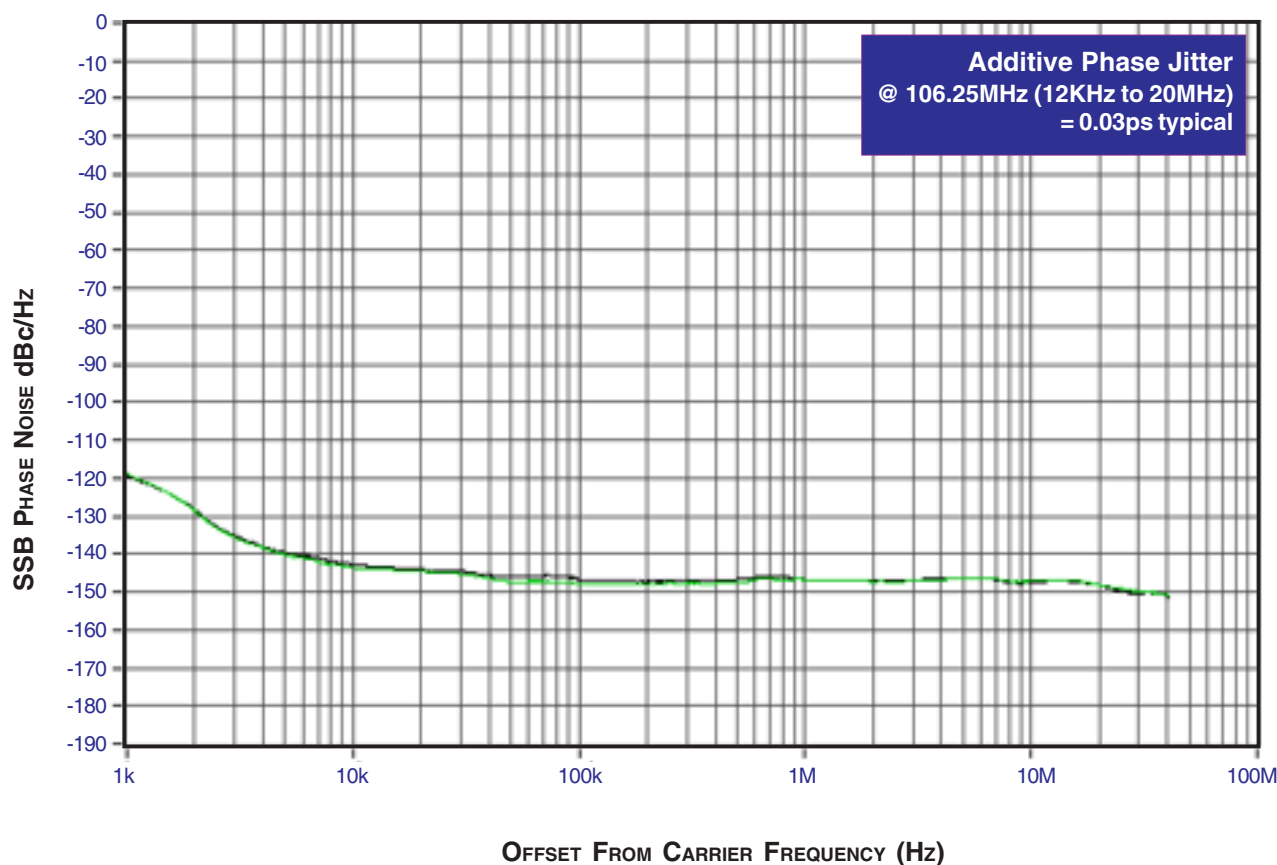
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.



ADDITIVE PHASE JITTER

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the ***dBc Phase Noise***. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power in

the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a ***dBc*** value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.

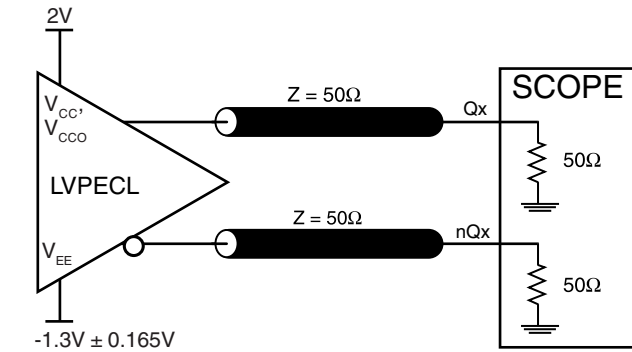


As with most timing specifications, phase noise measurements have issues. The primary issue relates to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The de-

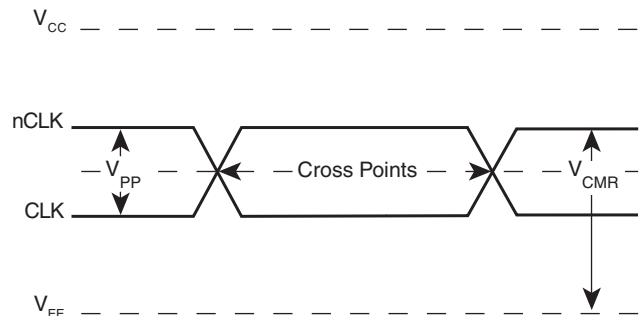
vice meets the noise floor of what is shown, but can actually be lower. The phase noise is dependant on the input source and measurement equipment.



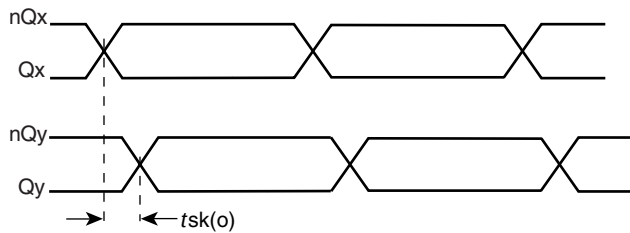
PARAMETER MEASUREMENT INFORMATION



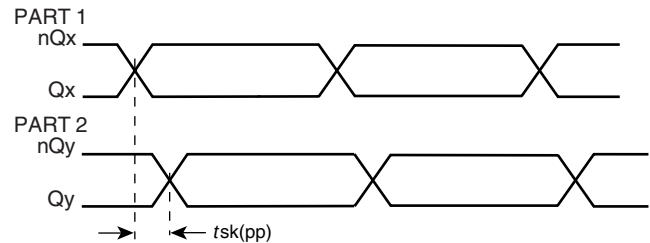
3.3V OUTPUT LOAD AC TEST CIRCUIT



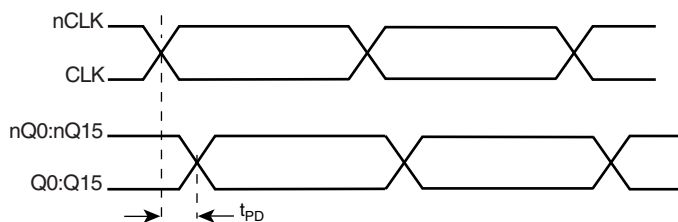
DIFFERENTIAL INPUT LEVEL



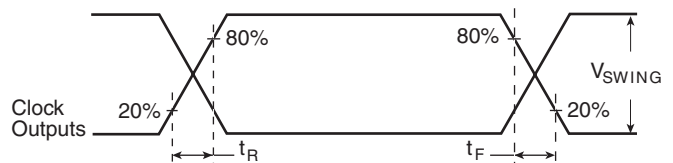
OUTPUT SKEW



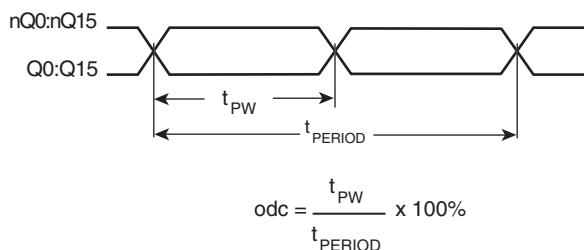
PART-TO-PART SKEW



PROPAGATION DELAY



OUTPUT RISE/FALL TIME



OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

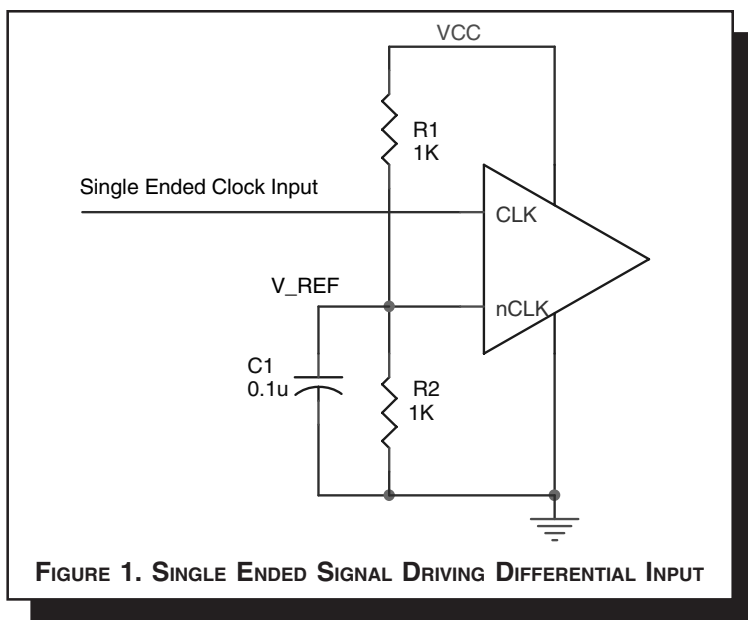


APPLICATION INFORMATION

WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage $V_{REF} \approx V_{CC}/2$ is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the

input pin. The ratio of R1 and R2 might need to be adjusted to position the V_{REF} in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and $V_{CC} = 3.3V$, V_{REF} should be 1.25V and $R2/R1 = 0.609$.



RECOMMENDATIONS FOR UNUSED OUTPUT PINS

OUTPUTS:

LVPECL OUTPUT

All unused LVPECL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.



DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSTL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. Figures 2A to 2E show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested

here are examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example in Figure 2A, the input termination applies for ICS HiPerClockS LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

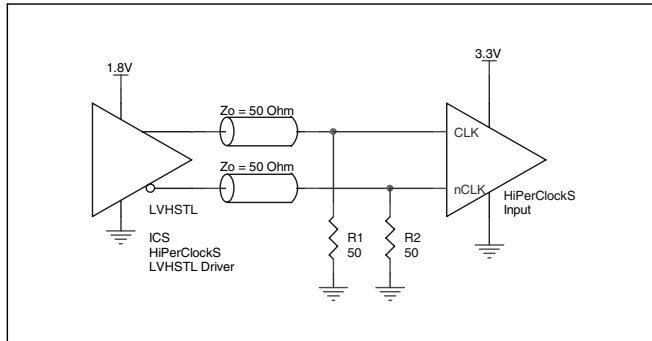


FIGURE 2A. HiPerClockS CLK/nCLK INPUT DRIVEN BY ICS HiPerClockS LVHSTL DRIVER

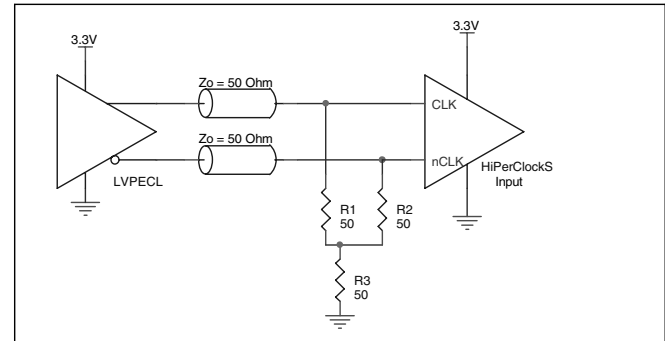


FIGURE 2B. HiPerClockS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

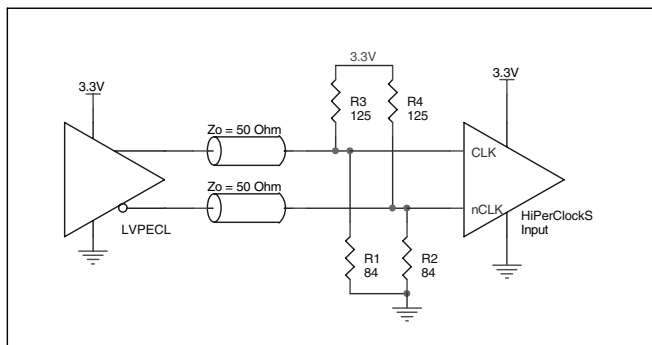


FIGURE 2C. HiPerClockS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

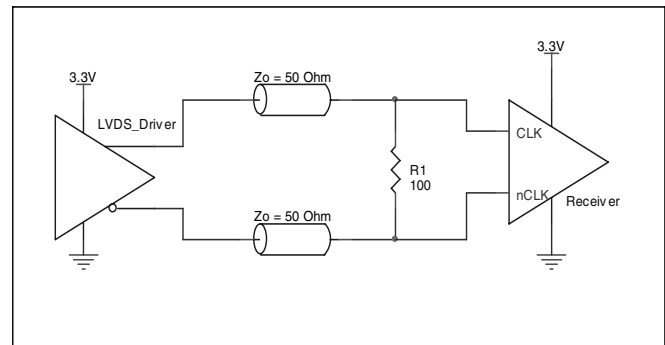


FIGURE 2D. HiPerClockS CLK/nCLK INPUT DRIVEN BY 3.3V LVDS DRIVER

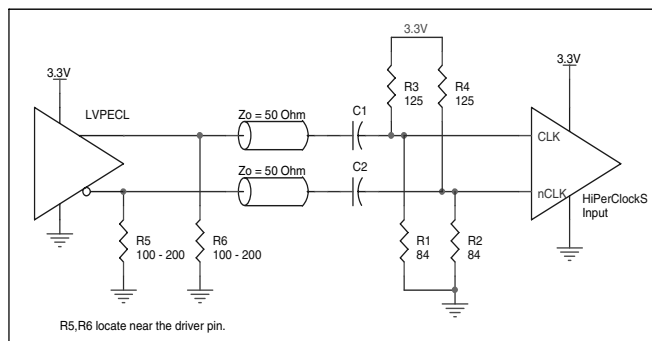


FIGURE 2E. HiPerClockS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER WITH AC COUPLE



TERMINATION FOR LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω transmission lines. Matched imped-

ance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 3A and 3B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

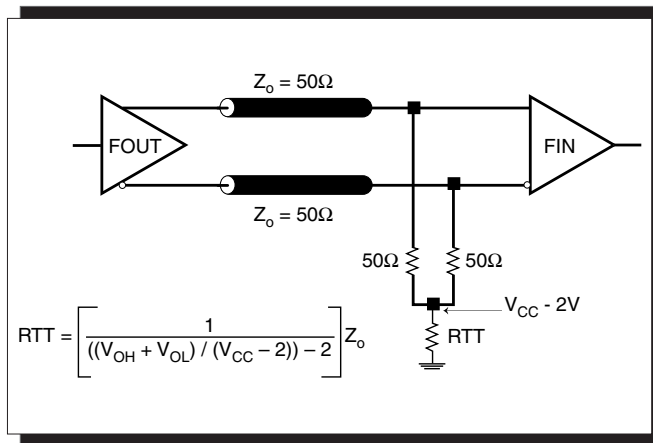


FIGURE 3A. LVPECL OUTPUT TERMINATION

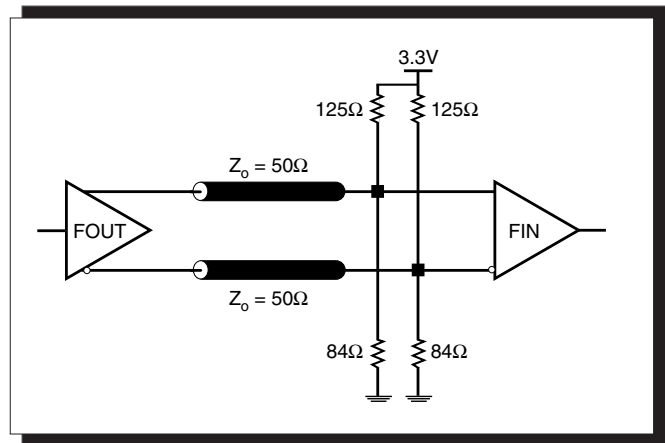


FIGURE 3B. LVPECL OUTPUT TERMINATION



POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS8530-01. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS8530-01 is the sum of the core power plus the power dissipated in the load(s).

The following is the power dissipation for $V_{CC} = 3.3V + 5\% = 3.465V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)_{MAX} = $V_{CC_MAX} * I_{EE_MAX} = 3.465V * 140mA = 485.1mW$
- Power (outputs)_{MAX} = **30.2mW/Loaded Output pair**
If all outputs are loaded, the total power is $16 * 30.2mW = 483.2mW$

$$\text{Total Power}_{MAX} (3.465V, \text{ with all outputs switching}) = 485.1mW + 483.2mW = 968.3mW$$

2. Junction Temperature.

Junction temperature, T_j , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for T_j is as follows: $T_j = \theta_{JA} * Pd_total + T_A$

T_j = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 47.9°C/W per Table 6 below.

Therefore, T_j for an ambient temperature of 70°C with all outputs switching is:

$$70^\circ C + 0.968W * 47.9^\circ C/W = 116.4^\circ C. \text{ This is below the limit of } 125^\circ C.$$

This calculation is only an example. T_j will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

TABLE 6. THERMAL RESISTANCE θ_{JA} FOR 48-PIN LQFP, FORCED CONVECTION

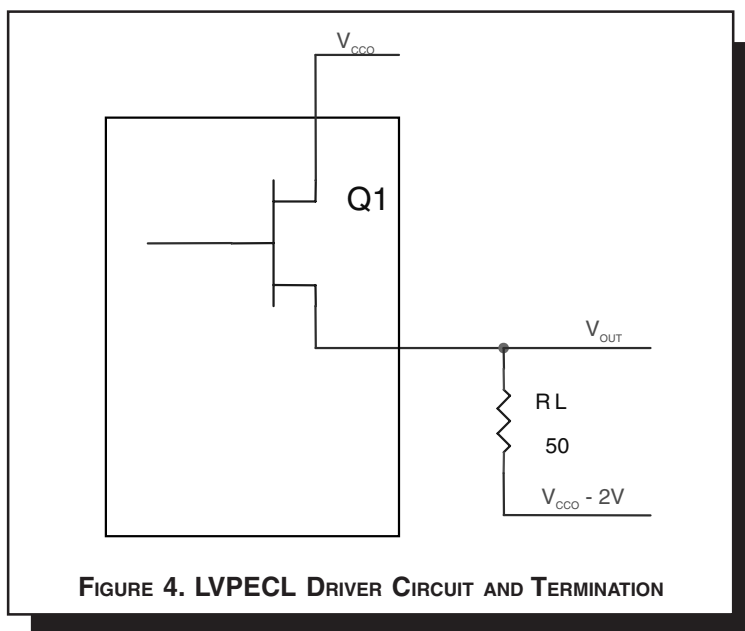
θ_{JA} by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W
NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.			



3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in Figure 4.



To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of $V_{CCO} - 2V$.

- For logic high, $V_{OUT} = V_{OH_MAX} = V_{CCO_MAX} - 1.0V$

$$(V_{CCO_MAX} - V_{OH_MAX}) = 1.0V$$

- For logic low, $V_{OUT} = V_{OL_MAX} = V_{CCO_MAX} - 1.7V$

$$(V_{CCO_MAX} - V_{OL_MAX}) = 1.7V$$

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$$Pd_H = [(V_{OH_MAX} - (V_{CCO_MAX} - 2V))/R_L] * (V_{CCO_MAX} - V_{OH_MAX}) = [(2V - (V_{CCO_MAX} - V_{OH_MAX}))/R_L] * (V_{CCO_MAX} - V_{OH_MAX}) = [(2V - 1V)/50\Omega] * 1V = 20.0mW$$

$$Pd_L = [(V_{OL_MAX} - (V_{CCO_MAX} - 2V))/R_L] * (V_{CCO_MAX} - V_{OL_MAX}) = [(2V - (V_{CCO_MAX} - V_{OL_MAX}))/R_L] * (V_{CCO_MAX} - V_{OL_MAX}) = [(2V - 1.7V)/50\Omega] * 1.7V = 10.2mW$$

$$\text{Total Power Dissipation per output pair} = Pd_H + Pd_L = 30.2mW$$



RELIABILITY INFORMATION

TABLE 7. θ_{JA} VS. AIR FLOW TABLE FOR 48 LEAD LQFP

θ_{JA} by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for ICS8530-01 is: 930



PACKAGE OUTLINE - Y SUFFIX FOR 48 LEAD LQFP

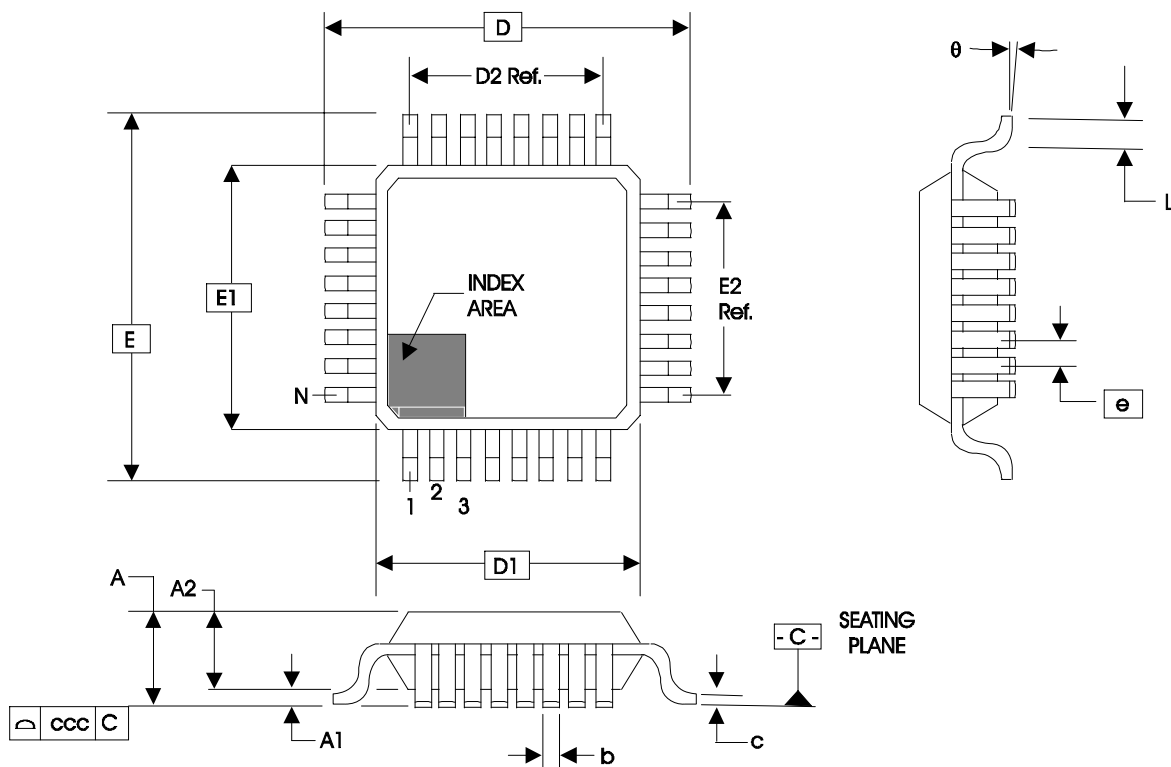


TABLE 8. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS			
SYMBOL	BBC		
	MINIMUM	NOMINAL	MAXIMUM
N	48		
A	--	--	1.60
A1	0.05	--	0.15
A2	1.35	1.40	1.45
b	0.17	0.22	0.27
c	0.09	--	0.20
D	9.00 BASIC		
D1	7.00 BASIC		
D2	5.50 Ref.		
E	9.00 BASIC		
E1	7.00 BASIC		
E2	5.50 Ref.		
e	0.50 BASIC		
L	0.45	0.60	0.75
θ	0°	--	7°
ccc	--	--	0.08

Reference Document: JEDEC Publication 95, MS-026



Integrated
Circuit
Systems, Inc.

ICS8530-01

LOW SKEW, 1-TO-16

DIFFERENTIAL-TO-3.3V LVPECL FANOUT BUFFER

TABLE 9. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS8530DY-01	ICS8530DY-01	48 Lead LQFP	tray	0°C to 70°C
ICS8530DY-01T	ICS8530DY-01	48 Lead LQFP	1000 tape & reel	0°C to 70°C
ICS8530DY-01LF	ICS8530D01LF	48 Lead "Lead-Free" LQFP	tray	0°C to 70°C
ICS8530DY-01LFT	ICS8530D01LF	48 Lead "Lead-Free" LQFP	1000 tape & reel	0°C to 70°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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REVISION HISTORY SHEET				
Rev	Table	Page	Description of Change	Date
B		5-6 7	Updated figures. Added Termination for LVPECL Outputs section.	05/28/02
B		2 5	Pin Description table - V_{CC} description changed to "Core supply pin" from "Positive supply pin". Output Load Test Circuit diagram - corrected VEE equation to read, $V_{EE} = -1.3V \pm 0.165V$ from $V_{EE} = -1.3V \pm 0.135V$.	10/02/02
C	T2 T4A	2 3 3 6 7 8	Pin Characteristics table - changed C_{IN} 4pF max. to 4pF typical. Updated AMR Output rating. Power Supply table - changed I_{EE} max. from 120mA to 140mA. Updated Single Ended Signal Driving Differential Input diagram. Added Differential Clock Input Interface section. Power Considerations, changed I_{EE} to 140mA to reflect the Power Supply table and recalculated the equations. Update format throughout the data sheet.	4/7/04
C	T9	12	Added "Lead-Free" marking to Ordering Information Table.	6/29/04
D	T5	1 4 5	Features section - added Additive Phase Jitter bullet. AC Characteristics table - added t_{jit} row. Added Additive Phase Jitter section.	2/28/05
E	T4C T9	3 7 14	LVPECL DC Characteristics - changed V_{SWING} (max) limit from 850mV to 1.0V. Corrected V_{OH} (max) limit from $V_{CCO} - 1.0V$ to $V_{CCO} - 0.9V$. Added <i>Recommendations for Unused Output Pins</i> . Ordering Information Table - added lead-free note.	5/19/06